

## Quantum Capacitance-Limited MoS<sub>2</sub> Biosensors Enable Remote Label-Free Enzyme Measurements

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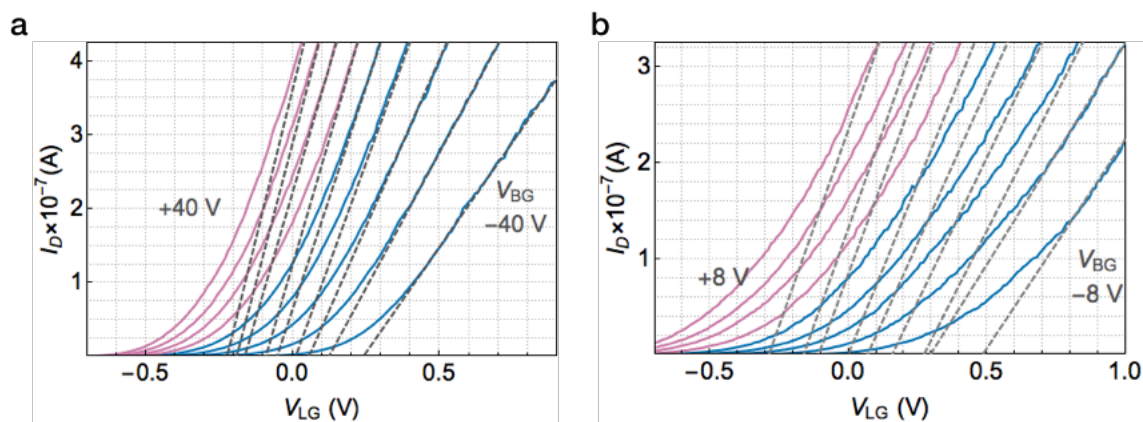


Fig. S1: The coupling between the ionic liquid and back gates was estimated from the transfer characteristics of the device. (a) When the back gate oxide thickness,  $d=300$  nm,  $\alpha=V_{BG}/V_{t,LG}$  was estimated to be 159 from the back gate voltage,  $V_{BG}$ , and shift in the liquid gate threshold voltage,  $V_{t,LG}$ . (b) When  $d=70$  nm,  $\alpha$  was lower as expected and estimated to equal 40.

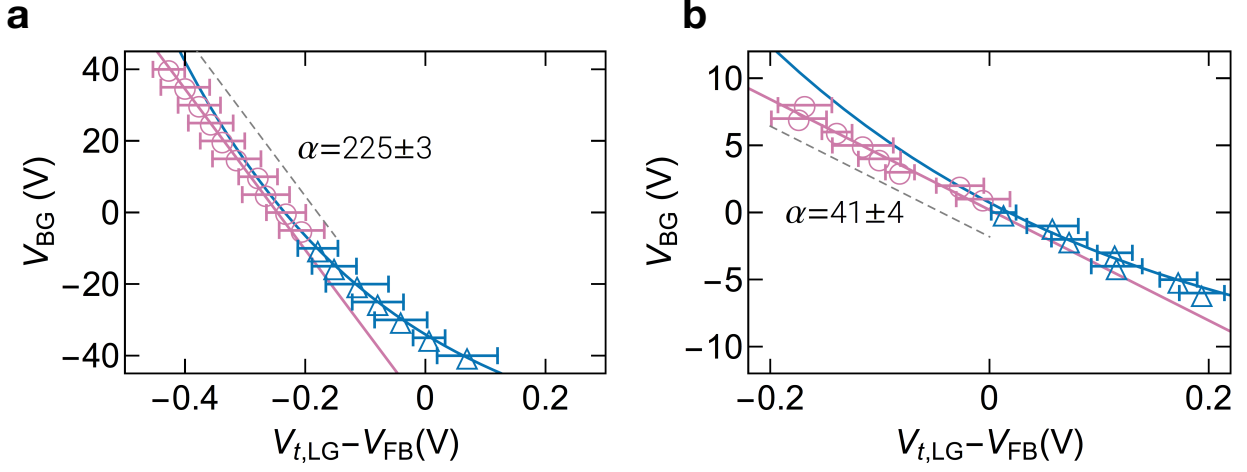


Fig. S2: The shift in the back gate voltage ( $V_{BG}$ ) plotted against the liquid gate threshold voltage ( $V_{t,LG}$ ) allowed the estimation of the gate coupling ratio ( $\alpha$ ). The flatband voltage ( $V_{FB}$ ) in both cases was assumed to be 0. (a) When the back gate oxide thickness ( $d$ ) was 300 nm, the maximum value of  $\alpha$  was estimated to be  $225 \pm 3$ . (b) The corresponding maximum value of  $\alpha$  when  $d = 70$  nm was  $41 \pm 4$ .

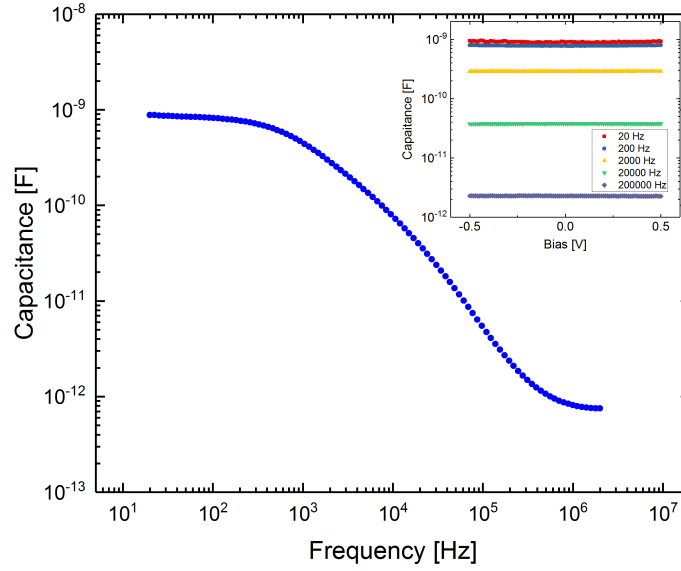


Fig. S3: AC impedance data for ionic liquid on gold electrodes.  $V_{AC} = 10$  mV, bias = 0 V. (inset) Capacitance with fixed frequency and measured with a variable voltage bias. We extracted the quantum capacitance value following a standard practice used previously when analyzing the performance of ionic liquid gated MoS<sub>2</sub> field effect transistor (Refs. 30 and 32 of the main text). Since, the quantum capacitance is an intrinsic property of MoS<sub>2</sub> and it depends on the carrier concentration within the channel, we are not aware of a way to directly measure its value outside of a field-effect-transistor (FET) structure, and in particular without coupling the channel to a gate dielectric to control the carrier density. Here, we performed a separate measurement of the capacitance of the room temperature ionic liquid used as the top gate dielectric. The measured ionic liquid gate capacitance value allowed us to extract the maximum quantum capacitance value of MoS<sub>2</sub> channel using model presented in the Method section. The extracted value compares favorably with both theory and previous experiment data confirming the approach of the method that we used in this paper.

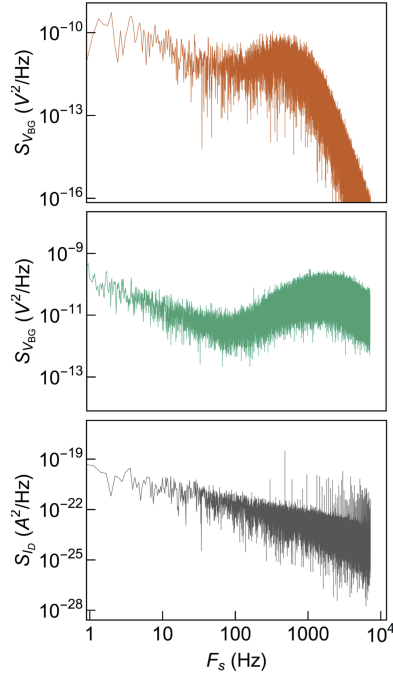


Fig. S4: The power spectral density of  $V_{BG}$  (300 nm SiO<sub>2</sub>, *top* and 70 nm SiO<sub>2</sub> *middle*) under PID control and  $I_D$  (300 nm SiO<sub>2</sub>, *bottom*) under open loop operation were used to estimate the signal to noise ratio (SNR).

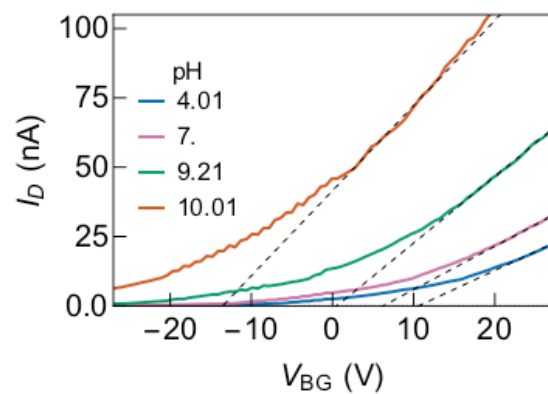


Fig. S5: The response of the sensor to standard pH buffers was estimated from the device transfer curves. The threshold voltage of the back oxide gate decreased when the solution pH measured with the ionic liquid gate became more acidic. The threshold voltage exhibited linear relationship with the solution pH over a wide range.

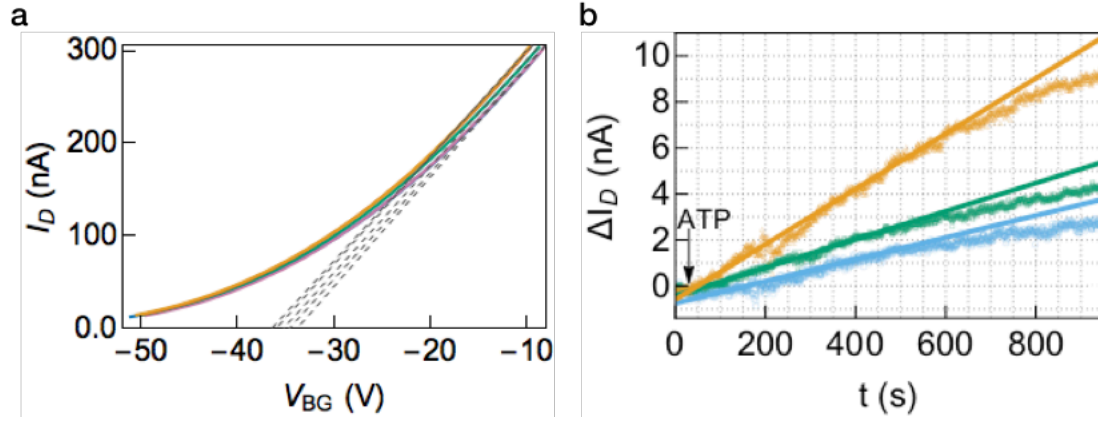


Fig. S6: Changes in the solution pH during enzyme catalyzed phosphorylation were used to estimate Cdk5 activity and dynamics. (a) Steady state measurements of the change in sensor  $I_D$ - $V_{BG}$  characteristics allowed the estimation of phosphorylation as a function of the substrate protein concentration. (b) The measurements were also performed dynamically by recording the current across the field effect transistor (FET) channel upon the initiation of the phosphorylation reaction with ATP for three concentrations of the substrate protein.

### Detailed Derivation of the Relationship Between the Gate Capacitances and Voltages

The detailed derivation of the relationship between  $C_{TG}/C_{BG}$  and  $dV_{BG}/dV_{t,LG}$  follows a classical model developed by Lim *et. al*<sup>1</sup> and later adapted by Jang *et. al*<sup>2-4</sup> for the case of ion sensing Si-FET and ionic liquid-gated MoS<sub>2</sub> FET. Fig. S3 depicts a simplified one-dimensional view of the active region of a dual-gated metal-oxide semiconductor field-effect transistor (MOSFET).

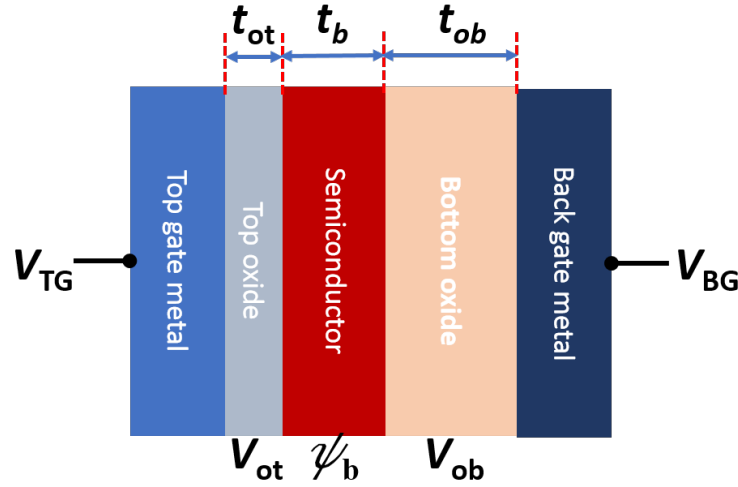


Fig. S7: One-dimensional active portion of the dual-gated field effect transistor (FET). For simplicity, the back gate is labeled “Back gate metal” even though it is typically heavily doped Si.

In analogy to bulk MOSFET theory,<sup>5</sup> we can write:

$$V_{TG} = \gamma_{ST} + V_{ot} + F_{t,MS} \quad (1)$$

and

$$V_{BG} = \gamma_{SB} + V_{ob} + F_{b,MS} \quad (2)$$

where  $V_{TG}$  and  $V_{BG}$  are the top and back gate voltages,  $\gamma_{ST}$  and  $\gamma_{SB}$  are the top and back surface potential at the semiconductor top and bottom oxide interfaces respectively,  $V_{ot}$  and  $V_{ob}$  are the potential drop across the top and back gate oxide,  $F_{t,MS}$  and  $F_{b,MS}$  are the differences in the metal and semiconductor work-functions.

Under normal operating conditions, the semiconductor is completely depleted. The potential drop across the semiconductor is then given by the expression:

$$\gamma_b = \gamma_{ST} - \gamma_{SB} = (E_{st} - qt_b N_a / (2e_s)) * t_b \quad (3)$$

where  $\mathbf{y_b}$  is the potential drop across the semiconductor,  $\mathbf{E_{st}}$  is the electric field at the top-surface edge of the depletion region, and  $\mathbf{N_a}$  is the doping density of the semiconductor (assuming p-type for an n-channel MOSFET),  $\mathbf{t_b}$  is the thickness of the semiconductor, and  $\mathbf{e_s}$  is the semiconductor dielectric constant.

Using Gauss's theorem for the top oxide semiconductor interface

$$V_{ot} = 1/C_{ot} * (\mathbf{e_s E_{st}} - Q_{ct}) \quad (4)$$

Similarly, for the bottom oxide semiconductor interface

$$-V_{ob} = 1/C_{ob} * (\mathbf{e_s E_{st}} - qN_a t_b - Q_{cb}) \quad (5)$$

where  $\mathbf{C_{ot(b)}}$  is the top(bottom) oxide capacitance,  $\mathbf{Q_{ct(b)}}$  is the inversion charge at the top(bottom) oxide/semiconductor interface. For simplicity, we did not take into account the fix charges and the interface states at the interfaces. Using equations 1, 3, and 4 we obtain:

$$V_{TG} = (1 + C_b/C_{ot}) \mathbf{y_{ST}} - C_b/C_{ot} * \mathbf{y_{SB}} - (Q_b/2 + Q_{ct})/C_{ot} + F_{t,MS} \quad (6)$$

where  $\mathbf{C_b = e_s/t_b}$  is the depletion charge capacitance and  $\mathbf{Q_b = -qN_a t_b}$  is the depletion charge density. Similarly using equations 2, 3, and 5 we obtain:

$$V_{BG} = (1 + C_b/C_{ob}) \mathbf{y_{SB}} - C_b/C_{ob} * \mathbf{y_{ST}} - (Q_b/2 + Q_{cb})/C_{ob} + F_{b,MS} \quad (7)$$

Equation 6 and 7 describe the coupling between the front and back gate potentials. When the back oxide/semiconductor interface is in the inversion or accumulation regime, the top gate threshold voltage is virtually independent of the back gate voltage.<sup>1</sup>

On the other hand, when considering the case of depleted back oxide/semiconductor interface, the threshold condition of the top oxide/semiconductor interface is  $\mathbf{y_{ST} = 2F_B}$  where  $\mathbf{F_B = (kT/q) * \ln(N_a/n_i)}$  where  $k$  is Boltzmann constant,  $T$  is temperature and  $n_i$  is the semiconductor intrinsic carrier density.

Using equations 6 and 7, the top gate threshold voltage depends on back gate voltage using the relationship:

$$V_{t,TG} = V_{t,TG,A} - C_b C_{ob} / (C_{ot} (C_b + C_{ob})) * (V_{BG} - V_{BG,A}) \quad (8)$$

where the constants  $V_{t,TG,A} = (1 + C_b/C_{ot}) 2F_B - Q_b/2C_{ot} + F_{t,MS}$  and  $V_{BG,A} = F_{b,MS} - C_b/C_{ob} * 2F_B - Q_b/2C_{ob}$ .

From equation 8, we have:



$$dV_{t,TG} = - C_b C_{ob} / (C_{ot}(C_b + C_{ob})) * dV_{BG} \quad (9)$$

In order to apply equation 9 to our ionic-liquid gated MoS<sub>2</sub> FET, we need to modify the model slightly. For a monolayer MoS<sub>2</sub>,  $t_b$  is  $\sim 0.7\text{nm}$ , which in turn causes  $C_b \gg C_{ob}$ . Additionally,  $C_{ob} \approx C_{BG}$  and  $C_{ot}$  need to be replaced by  $C_{LG} = C_{ot} C_Q / (C_{ot} + C_Q)$  to take into account the effect of the quantum capacitance. Finally, equation 9 must be rewritten as:

$$dV_{t,TG} = - C_{BG} / C_{LG} * dV_{BG} \quad \text{or} \quad dV_{BG} = - C_{LG} / C_{BG} * dV_{t,TG} \quad (10)$$

The negative sign in equation 10 implies that increasing  $V_{BG}$  will decrease  $V_{t,TG}$  since it is easier to accumulate carriers in the channel at positive back gate voltages.

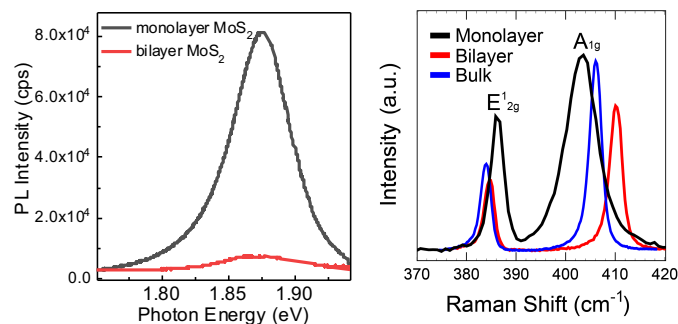


Fig. S8: (*left*) Photoluminescence (PL) spectra of monolayer and bilayer MoS<sub>2</sub>. Monolayer MoS<sub>2</sub> (*black*), which was used to fabricate devices in this study, possess a direct bandgap and exhibit a high PL intensity and a peak at  $\approx 1.87$  eV. In contrast, bilayer MoS<sub>2</sub> (*red*), which has an indirect bandgap has a greatly reduced PL intensity. (*right*) Raman spectra of MoS<sub>2</sub> used in this study. The A<sub>1g</sub> and E<sub>2g</sub> peak frequencies of  $404.1 \text{ cm}^{-1}$  and  $385.0 \text{ cm}^{-1}$  were used to verify that the film was a monolayer (*black*). The peak shifts of bilayer (*red*) and bulk films (*blue*) exhibit a distinct shift in the Raman peaks. *Adapted with permission from Guros et. al.*<sup>6</sup> Copyright 2019 American Chemical Society.

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